

Abstract

The invention relates to a method of assembling electric connector pins on a substrate (20) in the form of a board, consisting of inserting the pins (31) into individual housings (22) via a first face (20₁) of the substrate, the pins forming at least one comb-like alignment (31A, 31B) on the second face (20₂), arranging the solder on the second face of the substrate around the pins and heating the comb by means of a hot gaseous flow to achieve the soldering. The method is characterized in that the gaseous flow is guided so that it passes at least partially between the pins (31) forming the comb (31A, 31B) from one side of the comb then, after it has passed through the comb, it is diverted away from the substrate.

In particular, use is made of a nozzle having a channel to guide the gaseous flow and a deflector at least by which the flow is diverted. The wall of the channel is placed in line with the comb formed by the pins so as to reduce the portion of the flow not used for the heating.

Figure for the abstract: Figure 2